

What is claimed is:

1. A resin composition comprising:
styrene maleic anhydride co-polymer;
at least one epoxy resin;
at least one cross-linking agent;
talc; and
silica.
2. The resin of claim 1 wherein the talc is present in the resin in an amount ranging from about 2.5 to about 15 wt% on a dry basis.
3. The resin of any one of claims claim 1-2 wherein the silica is present in the resin in an amount ranging from about 2.5 to about 25 wt% on a dry basis.
4. The resin of any one of claims 1-3 wherein the silica is fused silica.
5. The resin of any one of claims 1-4 wherein the silica is a silated silica.
6. The resin of any one of claim 1-5 wherein the talc is a silated talc.
7. The resin of any one of claims 1-6 including from about 5 to about 12.5 wt% talc and from about 5 to about 25 wt% of silated fused silica each on a dry basis.
8. The resin of any one of claims 1-7 wherein the styrene maleic anhydride co-polymer is present in the resin in an amount ranging from about 5 to about 40 wt% on a dry basis.
9. The resin of any one of claims 1-8 wherein the at least one epoxy resin is

present in the resin in an amount ranging from about 10 to about 50 wt% on a dry basis.

10. The resin of any one of claims 1-9 wherein the at least one epoxy resin is selected from a brominated bisphenol A, a brominated bisphenol F, a non-brominated bisphenol A, a non-brominated bisphenol F and combinations thereof.

11. The resin of any one of claims 1-10 wherein the at least one cross-linking agent is present in the resin in an amount ranging from greater than 0 to about 20 wt% on a dry basis.

12. The resin of any one of claims 1-11 wherein the at least one cross-linking agent is selected from tetrabromobisphenol A, tetra-DOPO-bisphenol A and a mixture thereof.

13. The resin of any one of claims 1-12 including from about 0.01 to about 3.0 wt% on a dry basis of at least one azo-type catalyst.

14. The resin of any one of claims 1-13 including a catalyst selected from azobisisobutyronitrile, 2-propyl imidazole, tetrabutylphosphonium acid acetate, 2-methylimidazole and combinations thereof.

15. A resin composition comprising:

from about 5 to about 40 wt% on a dry solvent free resin basis of a styrene maleic anhydride co-polymer;

from about 10 to about 50 wt% on a dry solvent free resin basis of at least one epoxy resin is selected from a brominated bisphenol A, a brominated bisphenol F, a non-brominated bisphenol A, a non-brominated bisphenol F and combinations thereof;

from about greater than 0 to about 20 wt% on a dry solvent free resin basis of at least one cross-linking agent is selected from tetrabromobisphenol A, tetra-DOPO-bisphenol A and mixtures thereof;
from about 2.5 to about 15 wt% talc; and
from about 2.5 to about 15 wt% fumed silica.

16. The resin composition of claim 15 wherein the weight ratio of fumed silica to talc ranges from 1:2.5 to 5:1.
17. The resin composition of claim 15 wherein the weight ratio of fumed silica to talc ranges from 1:1 to 2.5:1.
18. The resin composition of claim 15 wherein the fumed silica is an amorphous silated fumed silica
19. The resin composition of claim 15 wherein the talc is silated talc.
20. The resin composition of claim 15 wherein the cross-linking agent is a mixture of tetrabromobisphenol A and tetra-DOPO-bisphenol A.
21. The resin composition of claim 15 wherein the catalyst is tetrabutylphosphonium acid acetate.
22. A prepreg including a reinforcing material impregnated with the resin of any of claims claim 1-21.
23. A laminate including a reinforcing material and the resin of any of claims 1-21 wherein the resin is C-staged.
24. A resin coated copper foil comprising a copper foil sheet having a first planar surface and a second planar surface wherein a layer of resin of any of claims 1-21 is applied to at least one of the planar surfaces and wherein the resin is B-staged or C-staged.
25. The prepreg of claim 22 wherein the prepreg is incorporated into a printed

circuit board and wherein the printed circuit board does not undergo delamination in the area of the prepreg.

26. The printed circuit board of claim 25 wherein the IR 260°C reflow wicking is 40 microns or less.